BRIGHTLASER

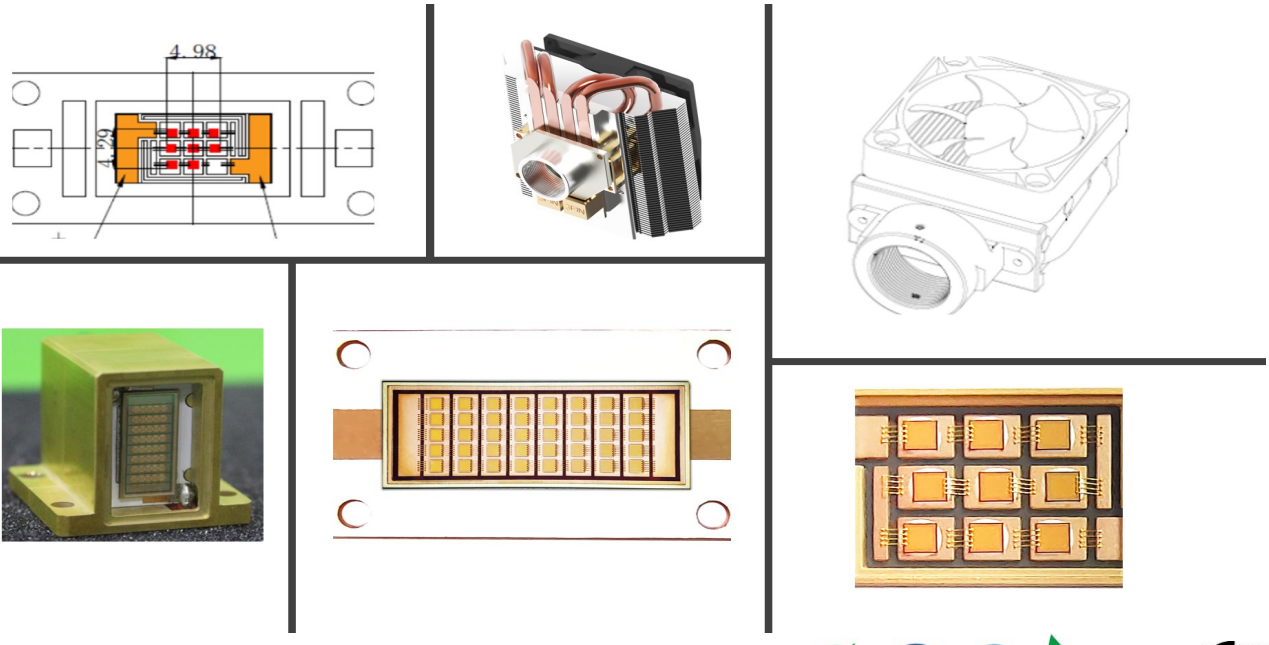
The competitive VCSEL & Photonic devices supplier

Brightlaser HK

VCSEL - High Power Assembly

Type	Characteristic of VCSEL Die				Package Forms	Applications Consumable Industrial Automotive
	Wavelength	Power / Peak Power	No. of Chips	Beam Angle (° Degree)		
High Power Assembly	660nm± 10nm 808nm± 10nm 850nm± 10nm 940nm± 10nm 1060nm± 10nm	6-15W	1 X 2 Chips	20-25	6868AIN/T-mount	Industrial Control
		10-60W	2 X 2 Chips	20-25	1408AIN/T-mount / Heatsink Module	
		20-100W	2 X 4 Chips	20-25	0613AIN/T-mount/Heatsink Module	Medical Application
		50-200W	4 X 6 Chips	20-25	2511AIN/T-mount/Heatsink Module	
		50-200W	5 X 5 Chips	20-25	2511AIN/T-mount/Heatsink Module	Security Surveillances
		60-300W	5 X 8 Chips	20-25	2511AIN/T-mount/Heatsink Module	
		XX ~ 1000W	100-300 chips	20-25	Customizable , Arbitrary Layout	

Type	Characteristic of VCSEL Die				Package Forms Single Chip / Chip Array	Applications Consumable Industrial Automotive
	Wavelength	Peak Power per Chip	No. of Aperture per Chip	Beam Angle (° Degree)		
High Power Assembly (Pulse Mode)	660nm± 10nm 808nm± 10nm 850nm± 10nm 940nm± 10nm 1060nm± 10nm	1-2W	1	20-25	Single Chip: 2016AIN/TO56 Chip Array: 1X4/1X8/1X16	Facial Recognition
		3-6W	3	20-25		
		10-25W	10	20-25		Human-Computer Interaction
		20-50W	20	20-25		
		50-100W	38	20-25		LiDAR
		100-400W	306	20-25	Single Chip: 3535AIN Chip Array: (customizable)	



Warning: Operating procedures and laser safety measures are essential to ensure the safe and proper use of the lasers.